

Proposed Document Structure

1. Introduction
2. Mechanical Specifications
 - 2.1 Wrapper
 - Form Factor
 - Retention Mechanisms
(References for existing mounting schemes may apply)
 - Assembly Tolerances
 - Cooling Considerations
 - Connector Specification (Parallel SCSI)
 - Device Connector
 - Contact Assignments
 - Device Key
 - 2.2 Envelope
 - Form Factor
 - Cooling Considerations
 - EMC Considerations
 - Assembly
 - Security
 - Logo Plate
 - User Areas
3. Electrical Specification
 - 3.1 Device Power
 - Maximum Power
 - Peak Power
 - Running Power
 - Stability
 - SES, SAF-TE, and SCA-2 References
4. Hot Plugging
 - 4.1 Completed Mated Notification
 - 4.2 SPI References